

Features

- Ultra low capacitance: 0.3pF(IO to IO)
- Ultra low leakage: nA level
- Low operating voltage: 5V
- Low clamping voltage
- Protects one power line and four data lines
- Flow-through package
- Complies with following standards:
 - IEC 61000-4-2 (ESD) immunity test
Air discharge: $\pm 25\text{kV}$
Contact discharge: $\pm 20\text{kV}$
 - IEC61000-4-4 (EFT) 40A (5/50ns)
 - IEC61000-4-5 (Lightning) 4A (8/20 μs)
- RoHS Compliant

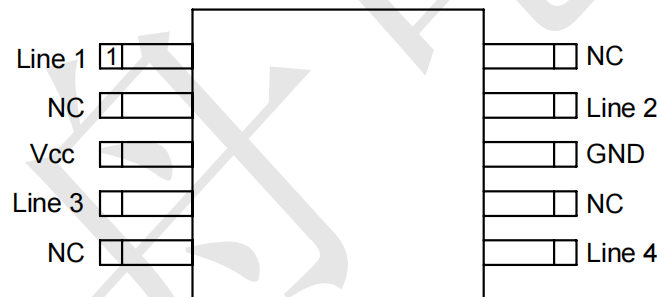
Mechanical Characteristics

- Package: MSOP-10
- Lead Finish: Matte Tin
- Case Material: "Green" Molding Compound.
- UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 3 per J-STD-020
- Shipping Qty :3000pcs/13Inch Tape & Reel

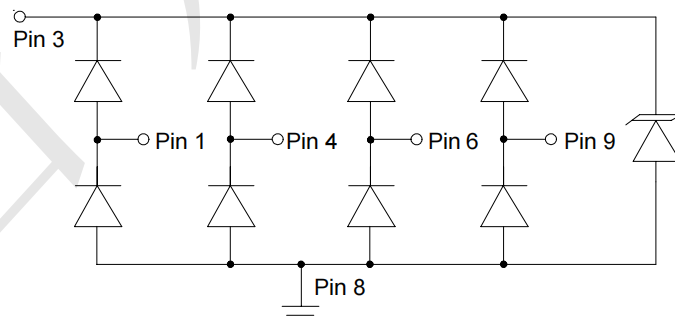
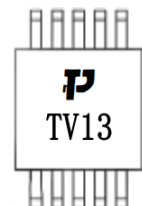
Applications

- DVI Ports
- HDMI Ports
- Set Top Box
- Projection TV
- Notebook Computers
- 10/100/1000 Ethernet

Dimensions and Pin Configuration



Marking:



Absolute Maximum Ratings ($T_A=25^{\circ}\text{C}$ unless otherwise specified)

Parameter	Symbol	Value	Unit
Peak Pulse Power (8/20 μs)	Ppk	100	W
Peak Pulse Current (8/20 μs)	I _{PP}	4	A
ESD per IEC 61000-4-2 (Air) ESD per IEC 61000-4-2 (Contact)	V _{ESD}	± 25 ± 20	kV
Operating Temperature Range	T _J	-55 to +125	$^{\circ}\text{C}$
Storage Temperature Range	T _{stg}	-55 to +150	$^{\circ}\text{C}$

Electrical Characteristics ($T_A=25^{\circ}\text{C}$ unless otherwise specified)

Parameter	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Working Voltage	V _{RWM}			5	V	Any I/O pin to ground
Breakdown Voltage	V _{BR}	6			V	I _T = 1mA, any I/O pin to ground
Reverse Leakage Current	I _R			1	μA	V _{RWM} = 5V, any I/O pin to ground
Clamping Voltage	V _C			14	V	I _{PP} = 1A (8 x 20 μs pulse), any I/O pin to ground
Clamping Voltage	V _C			20	V	I _{PP} = 4A (8 x 20 μs pulse), any I/O pin to ground
Junction Capacitance	C _J		0.7	1	pF	V _R = 0V, f = 1MHz, any I/O pin to ground
Junction Capacitance	C _J		0.3	0.6	pF	V _R = 0V, f = 1MHz, between I/O pins

Typical Performance Characteristics ($T_A=25^\circ\text{C}$ unless otherwise Specified)

Fig1. 8/20 μs Pulse Waveform

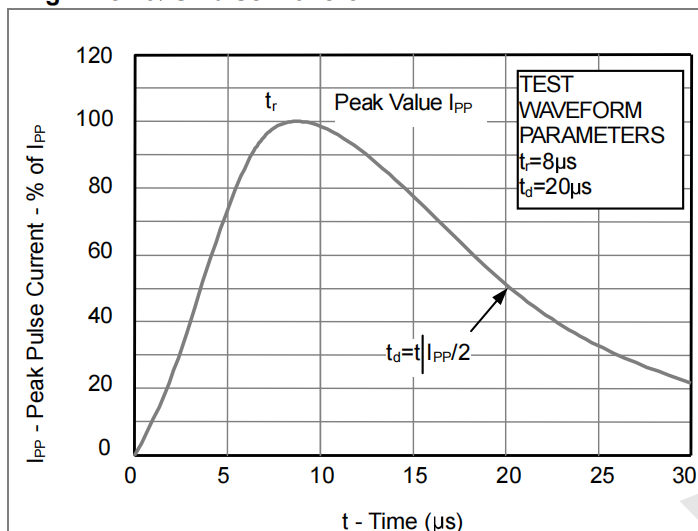


Fig2. ESD Pulse Waveform (according to IEC 61000-4-2)

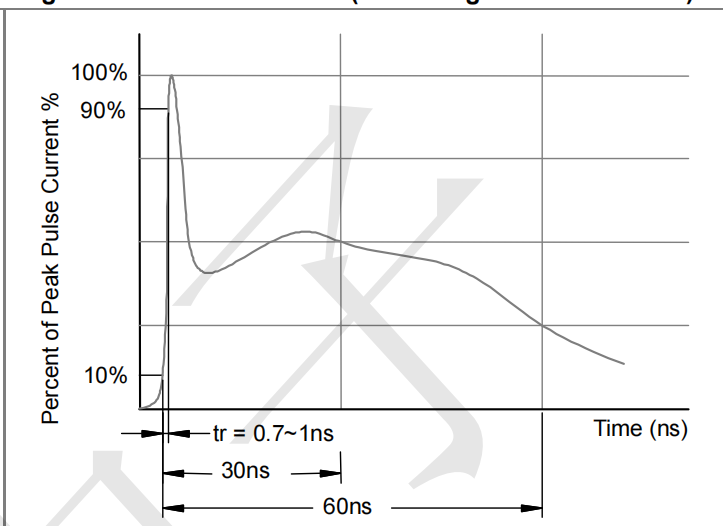
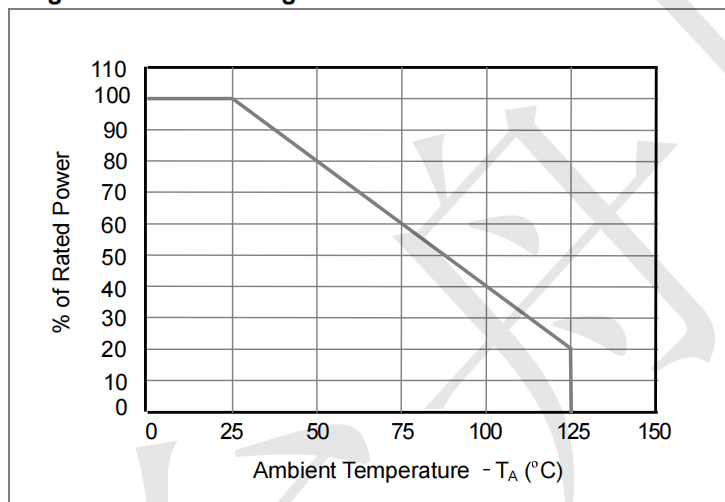
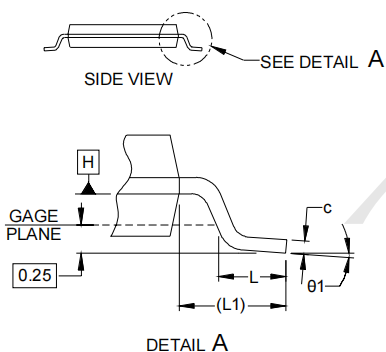
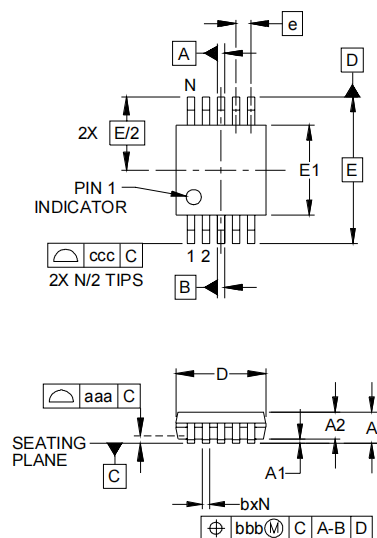


Fig3. Power Derating Curve

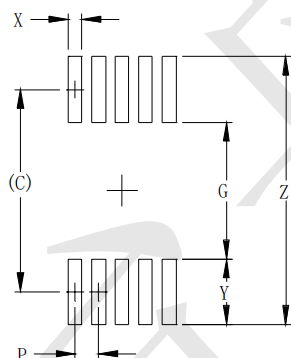


Outline Drawing -MSOP10



DIM	INCHES			MILLIMETERS		
	MIN	NOM	MAX	MIN	NOM	MAX
A	-	-	.043	-	-	1.10
A1	.000	-	.006	0.00	-	0.15
A2	.030	-	.037	0.75	-	0.95
b	.007	-	.011	0.17	-	0.27
c	.003	-	.009	0.08	-	0.23
D	.114	.118	.122	2.90	3.00	3.10
E1	.114	.118	.122	2.90	3.00	3.10
E	.193 BSC			4.90 BSC		
e	.020 BSC			0.50 BSC		
L	.016	.024	.032	0.40	0.60	0.80
L1	(.037)			(.95)		
N	10			10		
θ1	0°	-	8°	0°	-	8°
aaa	.004			0.10		
bbb	.003			0.08		
ccc	.010			0.25		

Land Pattern -MSOP-10



DIM	DIMENSIONS	
	INCHES	MILLIMETERS
C	(.161)	(4.10)
G	.098	2.50
P	.020	0.50
X	.011	0.30
Y	.063	1.60
Z	.224	5.70